

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2827
Examiner David A. Zarneke
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of the referenced art is respectfully requested.

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. 1.16 and 1.17 which may be required by this paper to Deposit Account No. 23-0925.

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Respectfully submitted,

Dated: 7-7-03

By:



D. Brent Kenady
Reg. No. 40,045

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